

Call for Papers



The International Symposium on Optical Memory and Optical Data Storage Topical Meeting 2011

26-30 June 2011

Kauai Marriott Resort & Beach Club, Lihue, Kauai Hawaii

Paper Submission Deadline: 11 February 2011

<http://www.photonicsconferences.org/ODS2011>

<http://www.isom.jp>

Sponsored by:

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The Institute of Image Electronics Engineers of Japan
The Institute of Image Information and Television Engineers
The Japan Society of Precision Engineering
The Laser Society of Japan



Scope:

Reflecting the international nature of the interest and work in optical memory and optical data storage, these two conferences are held jointly every third year. The unparalleled setting of this conference provides an outstanding opportunity to share the latest information in this dynamic field with your international colleagues.

The ISOM/ODS'11 offers an excellent forum for exchanging information on the status, advances, and future directions in the field of optical memory and optical data storage. Third generation high density recording systems using blue-violet lasers are growing in the commercial market. New developments in holographic, multi-dimensional, near-field, super-resolution, and hybrid recording technologies for the fourth generation systems will be the main focus at this conference.

New concepts based on nano-scale optical materials and phenomena will also be explored. Developments and methodologies in the areas of nano-photonics, plasmonics, spintronics, and bio-photonics are expected to influence future generation optical memory and optical data storage and will be in the spotlight of this conference. Contributions from a variety of areas spanning from basic theory and modeling, testing and characterization to manufacturing and production methods including media and materials, components, coding and signal processing, drive technologies, and systems and applications for industrial and consumer use will be presented.

Special sessions on new concepts such as nano-photonics and future emerging technologies are also planned. Contributions on alternative technologies and theoretical studies from universities are strongly encouraged. Invited talks in many of these areas will round out the four-day program. In addition to the technical sessions, a series of short courses on hot topics in several technological fields will be held on Sunday to educate both newcomers and veterans about the latest information in optical memory and optical data storage.

Topics:

- Holographic Recording
- Multi-dimensional Recording
- Near-field Recording
- Super-resolution
- Hybrid Recording
- Advanced or Related Technologies
- Basic Theory and Modeling
- Testing and Characterization
- Media and Materials
- Components
- Coding and Signal Processing
- Drive Technologies
- Systems and Applications
- Nano-photonics
- Plasmonics
- Spintronics
- Bio-photonics
- Future Emerging Technologies

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